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Gate Driver Providing Galvanic isolation Series

Isolation voltage 2500Vrms

1ch Gate Driver Providing Galvanic Isolation

BM60054FV-C

General Description

The BM60054FV-C is a gate driver with isolation voltage 2500Vrms, I/O delay time of 110ns, and a minimum input pulse width of 90ns. Fault signal output function, ready signal output function, under voltage lockout (UVLO) function, short current protection (SCP) function, and switching controller function are all built-in.

Key Specifications

■ Isolation Voltage:	2500Vrms
■ Maximum Gate Drive Voltage:	20V(Max)
■ I/O Delay Time:	110ns(Max)
■ Minimum Input Pulse Width:	90ns(Max)

Features

- Provides Galvanic Isolation
- Fault Signal Output Function
- Ready Signal Output Function
- Under Voltage Lockout Function
- Short Circuit Protection Function
- Soft Turn-Off Function for Short Circuit Protection (Adjustable Turn-OFF time)
- Thermal Protection Function
- Active Miller Clamping
- Switching Controller Function
- Output State Feedback Function
- UL1577 Recognized:File No. E356010
- AEC-Q100 Qualified^(Note 1) (Note 1:Grade1)

Package

SSOP-B28W

W(Typ) x D(Typ) x H(Max)

9.2 mm x 10.4 mm x 2.4 mm

Applications

- Driving IGBT Gate
- Driving MOSFET Gate

Typical Application Circuit

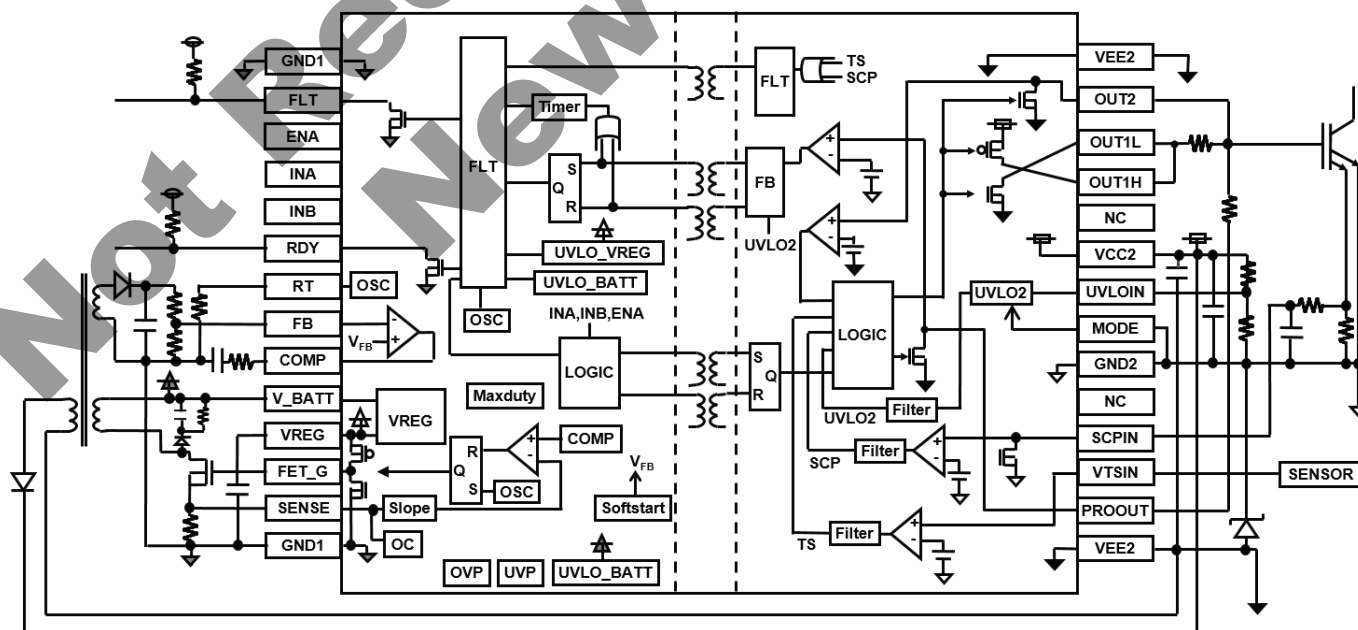


Figure 1. Typical Application Circuit

○Product structure : Silicon integrated circuit ○This product has no designed protection against radioactive rays

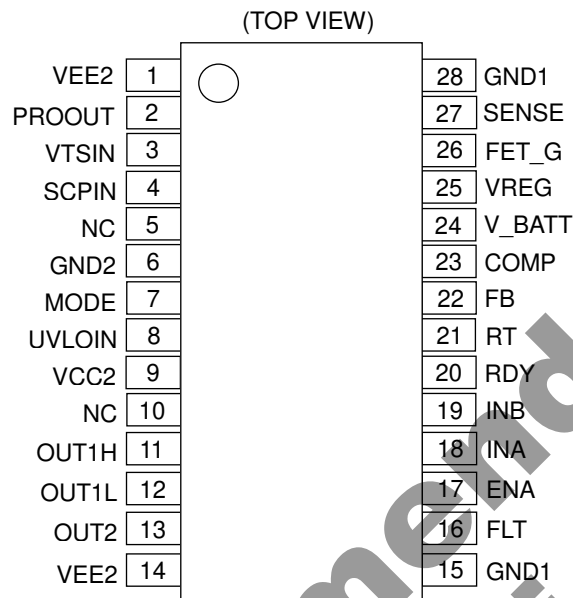
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Recommended Range of External Constants

Pin Name	Symbol	Recommended Value			Unit
		Min	Typ	Max	
VREG	C _{VREG}	1.0	3.3	10.0	μF
VCC2	C _{VCC2}	0.33	-	-	μF
RT	R _{RT}	24	68	150	kΩ

Pin Configuration



Pin Descriptions

	Pin Name	Pin Function
1	VEE2	Output-side negative power supply pin
2	PROOUT	Soft turn-off pin / Gate voltage input pin
3	VTSIN	Thermal detection pin
4	SCPIN	Short circuit current detection pin
5	NC	No connection
6	GND2	Output-side ground pin
7	MODE	Mode selection pin of output-side UVLO
8	UVLOIN	Output-side UVLO setting pin
9	VCC2	Output-side positive power supply pin
10	NC	No connection
11	OUT1H	Source side output pin
12	OUT1L	Sink side output pin
13	OUT2	Output pin for Miller Clamp
14	VEE2	Output-side negative power supply pin
15	GND1	Input-side ground pin
16	FLT	Fault output pin
17	ENA	Input enabling signal pin
18	INA	Control input pin A
19	INB	Control input pin B
20	RDY	Ready output pin
21	RT	Switching frequency setting pin for switching controller
22	FB	Error amplifier inverting input pin for switching controller
23	COMP	Error amplifier output pin for switching controller
24	V_BATT	Main power supply pin
25	VREG	Input-side internal power supply pin
26	FET_G	MOS FET control pin for switching controller
27	SENSE	Current detection pin for switching controller
28	GND1	Input-side ground pin

Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Main Power Supply Voltage	V _{BATT}	-0.3 to +40.0 ^(Note 2)	V
Output-Side Positive Supply Voltage	V _{CC2}	-0.3 to +24.0 ^(Note 3)	V
Output-Side Negative Supply Voltage	V _{EE2}	-15.0 to +0.3 ^(Note 3)	V
Maximum Difference Between Output-Side Positive and Negative Voltages	V _{MAX2}	30.0	V
INA, INB, ENA Pin Input Voltage	V _{IN}	-0.3 to +7.0 ^(Note 2)	V
MODE Pin Input Voltage	V _{MODE}	-0.3 to +V _{CC2} +0.3 or +24.0 ^(Note 3)	V
SCPIN Pin Input Voltage	V _{SCPIN}	-0.3 to +V _{CC2} +0.3 or +24.0 ^(Note 3)	V
VTSIN Pin Input Voltage	V _{VTS}	-0.3 to +V _{CC2} +0.3 or +24.0 ^(Note 3)	V
UVLOIN Pin Input Voltage	V _{UVLOIN}	-0.3 to +V _{CC2} +0.3 or +24.0 ^(Note 3)	V
OUT1H, OUT1L Pin Output Current (Peak 10μs)	I _{OUT1PEAK}	5.0 ^(Note 4)	A
OUT2 Pin Output Current (Peak 10μs)	I _{OUT2PEAK}	5.0 ^(Note 4)	A
PROOUT Pin Output Current (Peak 10μs)	I _{PROOUTPEA}	2.5 ^(Note 4)	A
FLT, RDY Pin Output Current	I _{FLT}	10	mA
FET_G Pin Output Current (Peak 1μs)	I _{FET_GPEAK}	1	A
Power Dissipation	P _d	1.12 ^(Note 5)	W
Operating Temperature Range	T _{opr}	-40 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Junction Temperature	T _{jmax}	+150	°C

(Note 2) Relative to GND1

(Note 3) Relative to GND2

(Note 4) Should not exceed P_d and T_j=150°C(Note 5) Derate above T_a=25°C at a rate of 9.5mW/°C. Mounted on a glass epoxy of 70 mm × 70 mm × 1.6 mm

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Main Power Supply Voltage ^(Note 6)	V _{BATT}	4.0	32	V
Output-Side Positive Supply Voltage ^(Note 7)	V _{CC2}	10	20	V
Output-Side Negative Supply Voltage ^(Note 7)	V _{EE2}	-12	0	V
Maximum Difference Between Output-Side Positive and Negative Voltages	V _{MAX2}	10	28	V
Switching frequency for switching controller	f _{SWR}	100	500	kHz

(Note 6) Relative to GND1

(Note 7) Relative to GND2

Insulation Related Characteristics (UL1577)

Parameter	Symbol	Characteristic	Unit
Insulation Resistance (V _{IO} =500V)	R _s	>10 ⁹	Ω
Insulation Withstand Voltage / 1 min	V _{ISO}	2500	V _{rms}
Insulation Test Voltage / 1 sec	V _{ISO}	3000	V _{rms}

Electrical Characteristics

(Unless otherwise specified $T_a = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{\text{BATT}} = 4.0\text{V}$ to 32V , $V_{\text{CC2}} = \text{UVLO}$ to 20V , $V_{\text{EE2}} = -12\text{V}$ to 0V)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
General						
Main Power Supply Circuit Current 1	I_{BATT1}	1.1	1.6	2.1	mA	$V_{\text{BATT}} = 4.0\text{V}$
Main Power Supply Circuit Current 2	I_{BATT2}	0.8	1.3	1.8	mA	$V_{\text{BATT}} = 12.0\text{V}$
Main Power Supply Circuit Current 3	I_{BATT3}	0.8	1.3	1.8	mA	$V_{\text{BATT}} = 32.0\text{V}$
Output Side Circuit Current 1	I_{CC21}	0.7	1.4	2.1	mA	$V_{\text{CC2}} = 14\text{V}$, $\text{OUT1} = \text{L}$
Output Side Circuit Current 2	I_{CC22}	0.4	1.1	1.8	mA	$V_{\text{CC2}} = 14\text{V}$, $\text{OUT1} = \text{H}$
Output Side Circuit Current 3	I_{CC23}	0.8	1.5	2.2	mA	$V_{\text{CC2}} = 18\text{V}$, $\text{OUT1} = \text{L}$
Output Side Circuit Current 4	I_{CC24}	0.8	1.2	1.9	mA	$V_{\text{CC2}} = 18\text{V}$, $\text{OUT1} = \text{H}$
Output Side Circuit Current 5	I_{CC25}	0.9	1.6	2.3	mA	$V_{\text{CC2}} = 16\text{V}$, $V_{\text{EE2}} = -8\text{V}$, $\text{OUT1} = \text{L}$
Output Side Circuit Current 6	I_{CC26}	0.6	1.3	2.0	mA	$V_{\text{CC2}} = 16\text{V}$, $V_{\text{EE2}} = -8\text{V}$, $\text{OUT1} = \text{H}$
Switching Power Supply Controller						
FET_G Output Voltage H1	V_{FETGH1}	3.8	4.0	4.2	V	$4.2\text{V} < V_{\text{BATT}} \leq 32\text{V}$ $I_{\text{FET_G}} = 0\text{A}(\text{open})$
FET_G Output Voltage H2	V_{FETGH2}	-	$V_{\text{BATT}} - 0.2$	V_{BATT}	V	$V_{\text{BATT}} \leq 4.2\text{V}$ $I_{\text{FET_G}} = 0\text{A}(\text{open})$
FET_G Output Voltage L	V_{FETGL}	0	-	0.3	V	$I_{\text{FET_G}} = 0\text{A}(\text{open})$
FET_G ON-Resistance (Source-side)	R_{ONGH}	3	6	12	Ω	10mA
FET_G ON-Resistance (Sink-side)	R_{ONGL}	0.3	0.6	1.3	Ω	10mA
Oscillation Frequency	f_{SW}	182	200	222	kHz	$R_{\text{T}} = 68\text{k}\Omega$
Soft-start Time	t_{SS}	-	-	50	ms	
FB Pin Threshold Voltage	V_{FB}	1.47	1.50	1.53	V	
FB Pin Input Current	I_{FB}	-0.8	0	0.8	μA	
COMP Pin Sink Current	I_{COMPSINK}	-160	-80	-40	μA	
COMP Pin Source Current	$I_{\text{COMPSOURCE}}$	40	80	160	μA	
V_{BATT} UVLO ON Voltage	$V_{\text{UVLOBATTL}}$	3.20	3.40	3.60	V	
V_{BATT} UVLO Hysteresis	$V_{\text{UVLOBATHYS}}$	0.07	0.1	0.13	V	
Maximum ON DUTY	D_{ONMAX}	-	48	-	%	
Over Voltage Detection Threshold	V_{OVTH}	1.60	1.65	1.70	V	
Under Voltage Detection Threshold	V_{UVTH}	1.23	1.30	1.37	V	
Over-Current Detection Threshold	V_{OCTH}	0.17	0.20	0.23	V	
Protection Holding Time	t_{DCDCLS}	20	40	60	ms	
Logic Block						
Logic High Level Input Voltage	V_{INH}	2.0	-	5.5	V	INA, INB, ENA
Logic Low Level Input Voltage	V_{INL}	0	-	0.8	V	INA, INB, ENA
Logic Pull-Down Resistance	R_{IND}	25	50	100	$\text{k}\Omega$	INA, INB, ENA
Logic Input Filtering Time	t_{INFIL}	-	-	90	ns	INA, INB
ENA Input Filtering Time	t_{ENAFIL}	-	0.5	0.8	μs	ENA
MODE Low Level Input Voltage	V_{MODEL}	0	-	$0.3 \times V_{\text{CC2}}$	V	MODE, relative to GND2
MODE High Level Input Voltage	V_{MODEH}	$0.7 \times V_{\text{CC2}}$	-	V_{CC2}	V	MODE, relative to GND2

Electrical Characteristics – continued

(Unless otherwise specified $T_a = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{\text{BATT}} = 4.0\text{V}$ to 32V , $V_{\text{CC2}} = \text{UVLO}$ to 20V , $V_{\text{EE2}} = -12\text{V}$ to 0V)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Output						
OUT1H ON-Resistance	R_{ONH}	0.50	0.85	1.45	Ω	$I_{\text{OUT1H}} = 40\text{mA}$
OUT1L ON-Resistance	R_{ONL}	0.25	0.45	0.80	Ω	$I_{\text{OUT1L}} = 40\text{mA}$
OUT1 Maximum Current	I_{OUT1MAX}	3.0	4.5	-	A	$V_{\text{CC2}} = 15\text{V}$ Design assurance
PROOUT ON-Resistance	R_{ONPRO}	0.45	0.85	1.55	Ω	$I_{\text{PROOUT}} = 40\text{mA}$
Turn ON Time	t_{PONA}	45	75	105	ns	INA=PWM, INB=L
	t_{PONB}	50	80	110	ns	INA=H, INB=PWM
Turn OFF Time	t_{POFFA}	40	70	100	ns	INA=PWM, INB=L
	t_{POFFB}	35	65	95	ns	INA=H, INB=PWM
Propagation Distortion	t_{PDISTA}	-25	-5	15	ns	$t_{\text{POFFA}} - t_{\text{PONA}}$
	t_{PDISTB}	-35	-15	5	ns	$t_{\text{POFFB}} - t_{\text{PONB}}$
Rise Time	t_{RISE}	-	50	-	ns	10nF between OUT1-VEE2
Fall Time	t_{FALL}	-	50	-	ns	Design assurance
OUT2 ON-Resistance	R_{ON2}	0.25	0.45	0.80	Ω	$I_{\text{OUT2}} = 40\text{mA}$
OUT2 ON Threshold Voltage	V_{OUT2ON}	1.8	2	2.2	V	Relative to VEE2
Common Mode Transient Immunity	CM	100	-	-	kV/ μs	Design assurance
Protection Functions						
Output-side UVLO ON Threshold Voltage	V_{UVLOINL}	0.85	0.90	0.95	V	UVLOIN, MODE=L
Output-side UVLO Threshold Hysteresis	$V_{\text{UVLOINHYS}}$	$0.10 \times V_{\text{UVLOINL}}$	$0.11 \times V_{\text{UVLOINL}}$	$0.12 \times V_{\text{UVLOINL}}$	V	UVLOIN, MODE=L
Output-side UVLO ON Voltage	V_{UVLO2L}	10.9	11.5	12.1	V	V_{CC2} , MODE=H
Output-side UVLO Hysteresis	V_{UVLO2HYS}	0.8	1.2	1.6	V	V_{CC2} , MODE=H
Output-side UVLO Filtering Time	t_{UVLO2FIL}	0.25	1.5	3.7	μs	
DESAT Leading Edge Blanking Time	t_{DESATleb}	0.14	0.20	0.26	μs	Design assurance
Short Current Detection Voltage	V_{SCDET}	0.47	0.50	0.53	V	Relative to GND2
Short Current Detection Filter Time	t_{SCFIL}	0.12	0.2	0.28	μs	
Short Current Detection Delay Time (PROOUT)	t_{SCPPRO}	0.26	0.38	0.50	μs	
SCPIN Pin Low Voltage	V_{SCPINL}	-	0.1	0.22	V	$I_{\text{SCPIN}} = 1\text{mA}$
Output Delay Difference between PROOUT and FLT	t_{PROFLT}	0.1	0.4	0.7	μs	
Thermal Detection Voltage	V_{TSDET}	1.61	1.70	1.79	V	Relative to GND2
Thermal Detection Filter Time	t_{TSFIL}	4	10	30	μs	
Soft Turn Off Release Time	t_{STO}	30	-	110	μs	
FLT Output Low Voltage	V_{FLTL}	-	0.18	0.40	V	$I_{\text{FLT}} = 5\text{mA}$
Gate State H Detection Threshold Voltage	V_{OSFBH}	4.5	5.0	5.5	V	Relative to GND2
Gate State L Detection Threshold Voltage	V_{OSFBL}	4.0	4.5	5.0	V	Relative to GND2
OSFB Output Filtering Time	t_{OSFBFIL}	1.5	2.0	2.5	μs	
RDY Output Low Voltage	V_{RDYL}	-	0.18	0.40	V	$I_{\text{RDY}} = 5\text{mA}$

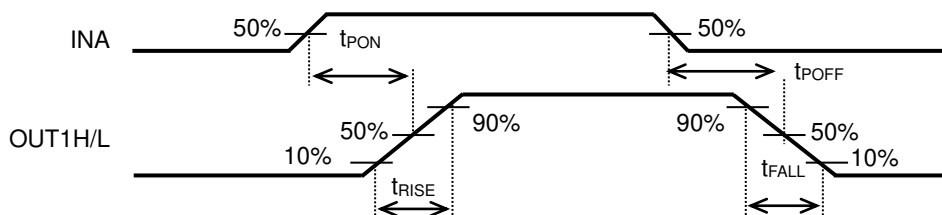


Figure 2. INA-OUT1H/L Timing Chart

UL1577 Ratings Table

Following values are described in UL Report.

Parameter	Values	Units	Conditions
Side 1 (Input Side) Circuit Current	1.3	mA	V_BATT=12V, OUT1H/L=L
Side 2 (Output Side) Circuit Current	1.6	mA	VCC2=18V, VEE2=-6V, OUT1H/L=L
Side 1 (Input Side) Consumption Power	15.6	mW	V_BATT=12V, OUT1H/L=L
Side 2 (Output Side) Consumption Power	38.4	mW	VCC2=18V, VEE2=-6V, OUT1H/L=L
Isolation Voltage	2500	Vrms	
Maximum Operating (Ambient) Temperature	125	°C	
Maximum Junction Temperature	150	°C	
Maximum Storage Temperature	150	°C	
Maximum Data Transmission Rate	5.5	MHz	

Not Recommended for New Designs

Typical Performance Curves

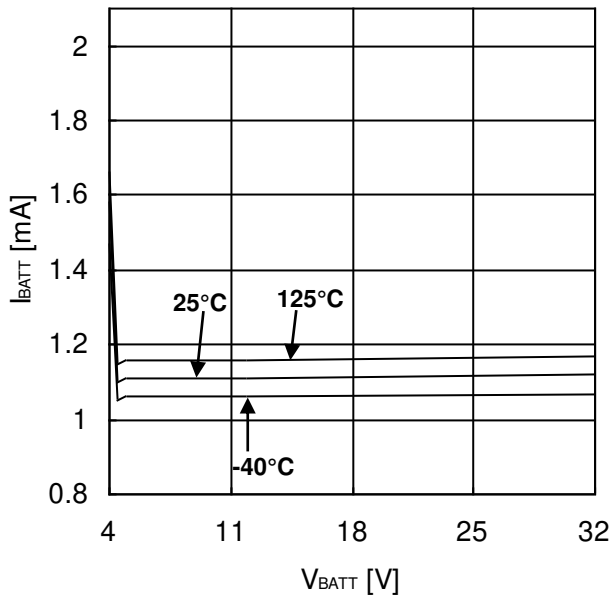


Figure 3. Main Power Supply Circuit Current

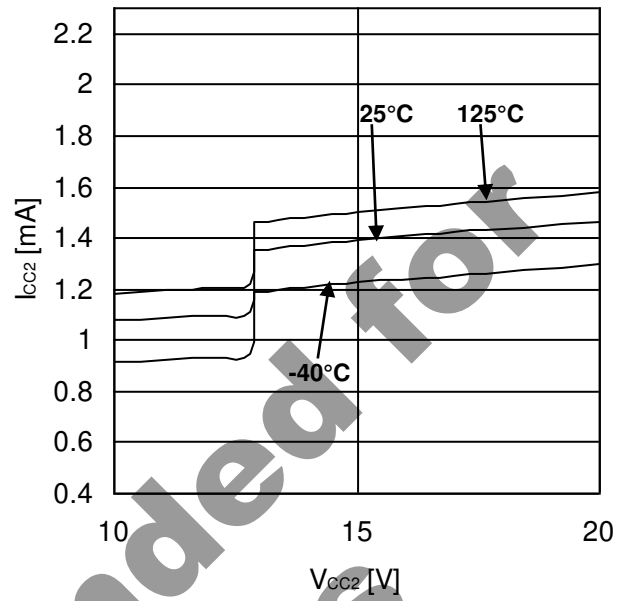


Figure 4. Output Side Circuit Current (MODE=H, VEE2=0V, OUT1=L)

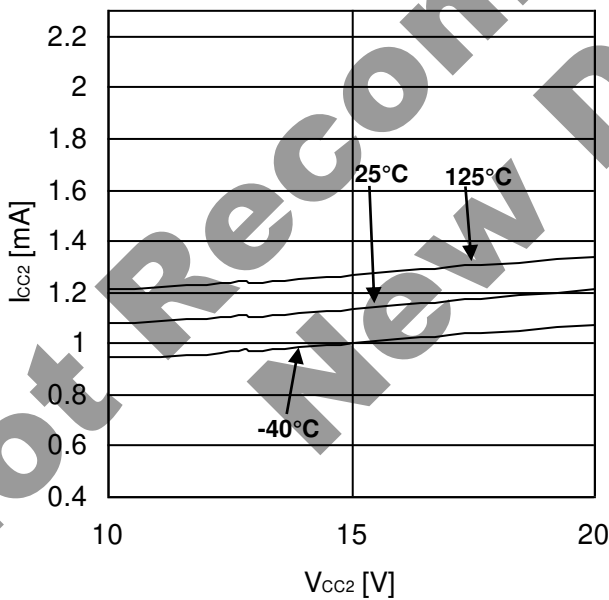


Figure 5. Output Side Circuit Current (MODE=H, VEE2=0V, OUT1=H)

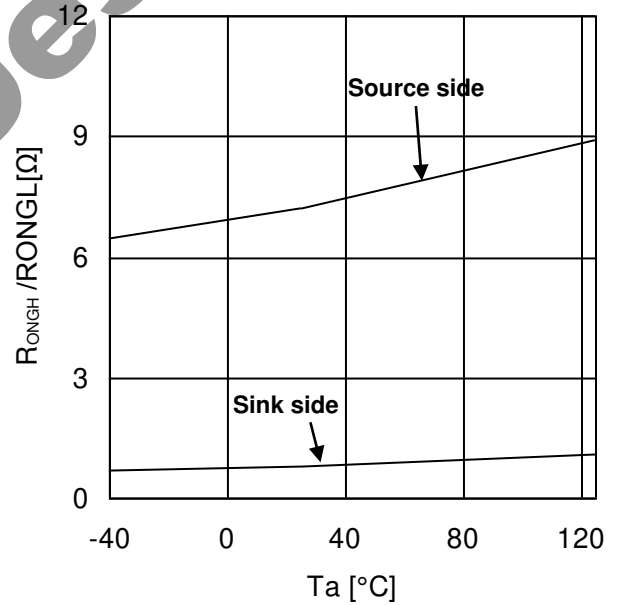


Figure 6. FET_G ON-Resistance (Source side/Sink side)

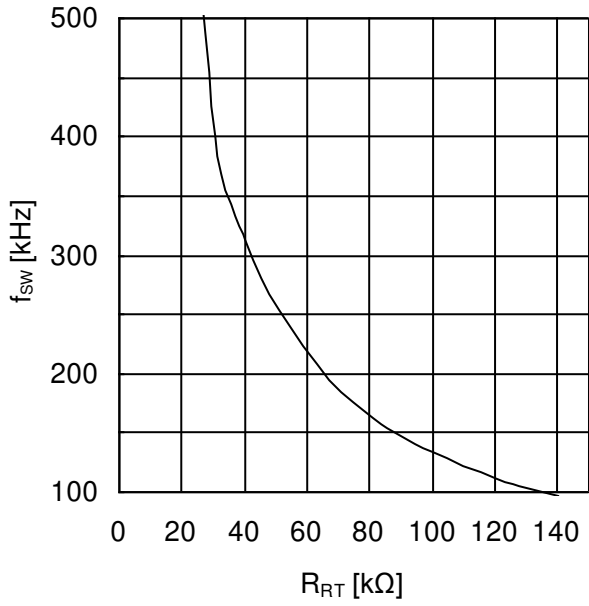


Figure 7. Oscillation Frequency

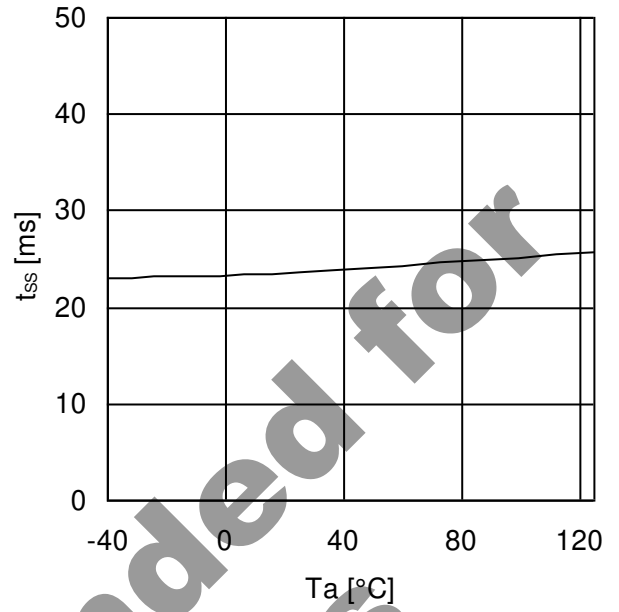


Figure 8. Soft-start Time

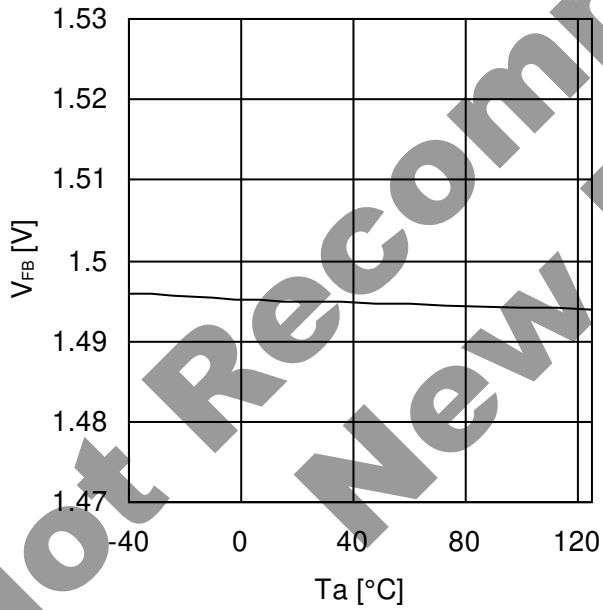


Figure 9. FB Pin Threshold Voltage

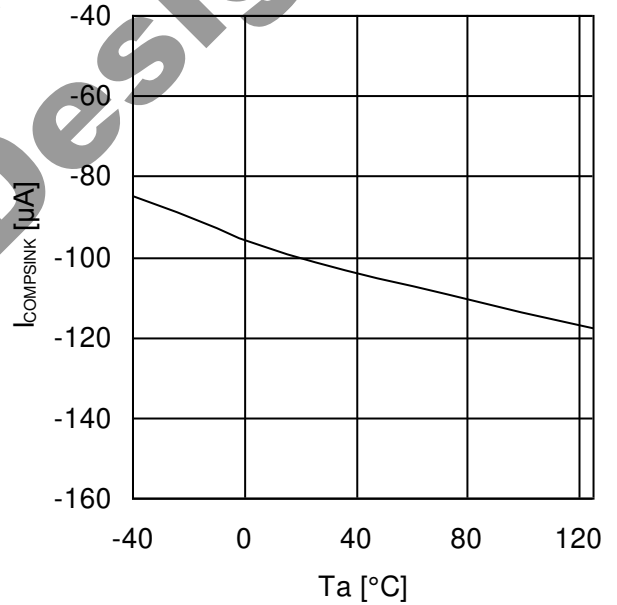


Figure 10. COMP Pin Sink Current

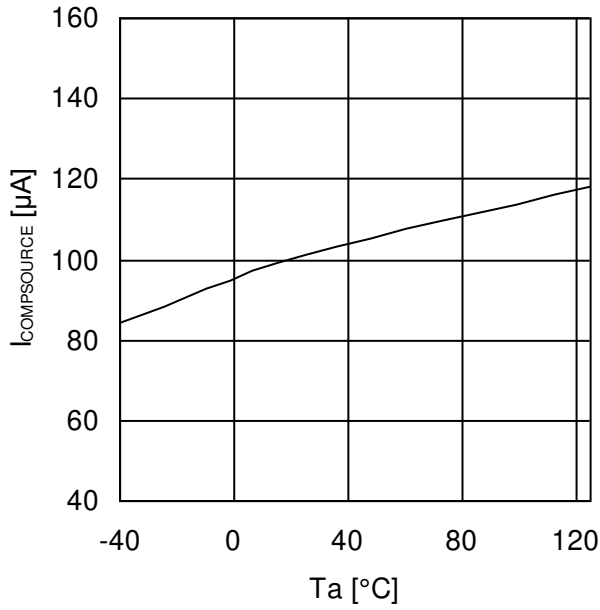


Figure 11. COMP Pin Source Current

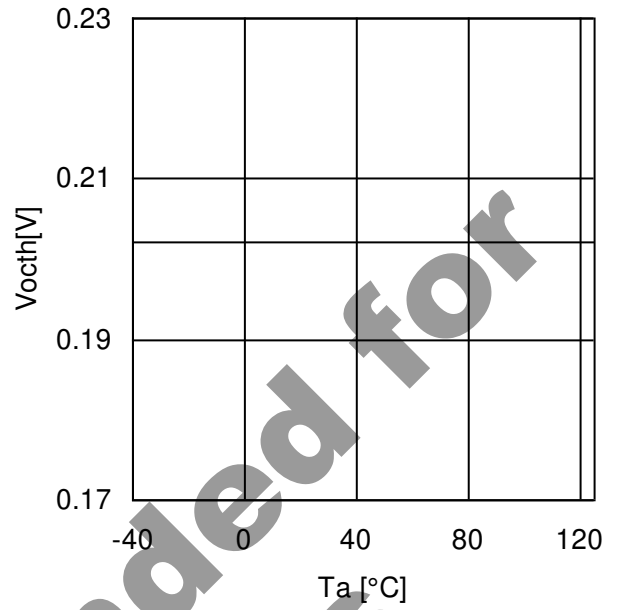


Figure 12. Over-Current Detection Threshold

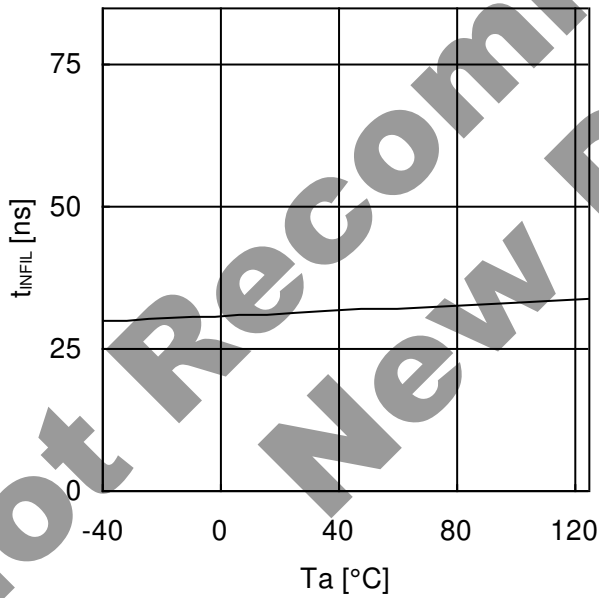


Figure 13. Logic Input Filtering Time (L pulse)

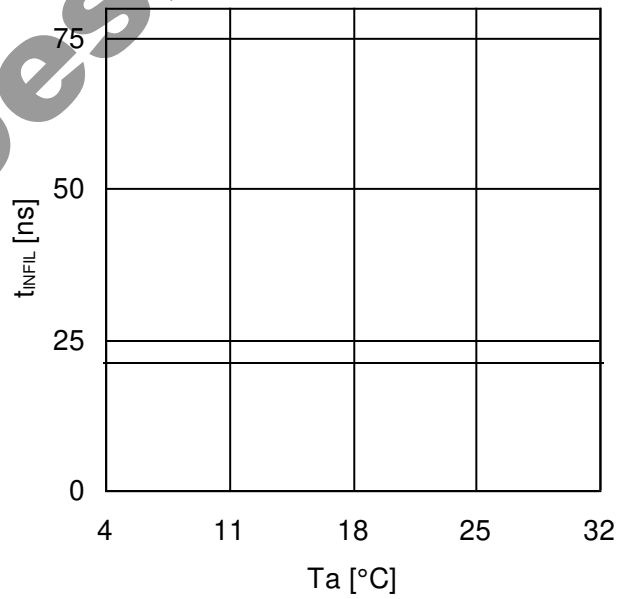


Figure 14. Logic Input Filtering Time (H pulse)

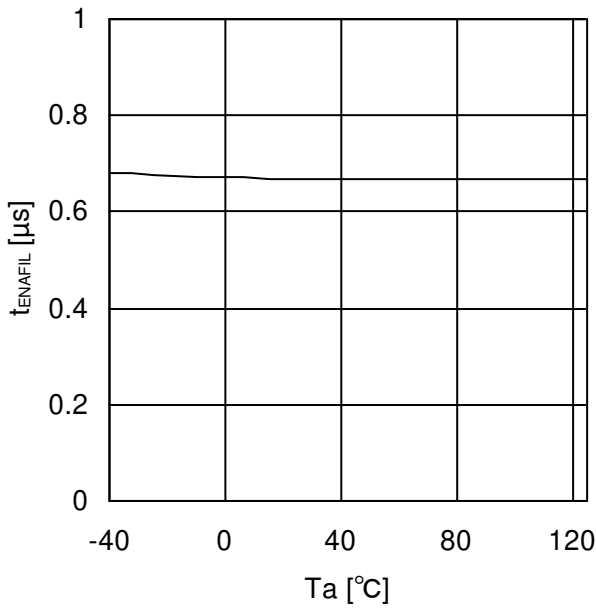


Figure 15. ENA Input Filtering Time

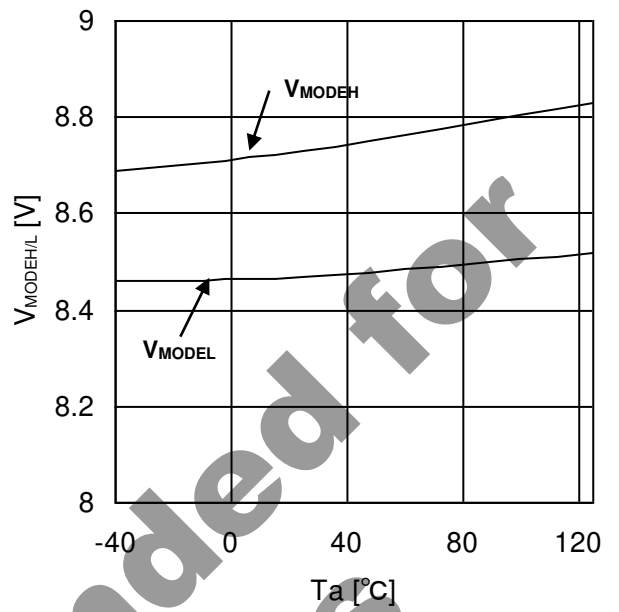


Figure 16. MODE Input Voltage H/L

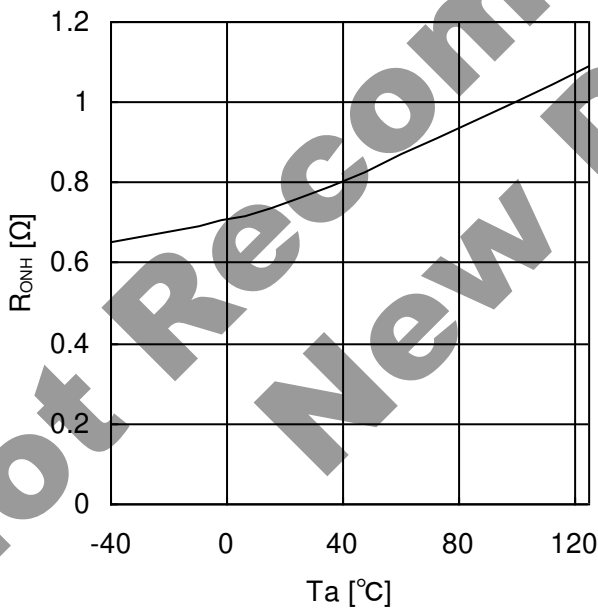


Figure 17. OUT1H ON-Resistance (I_{OUT1}=40mA)

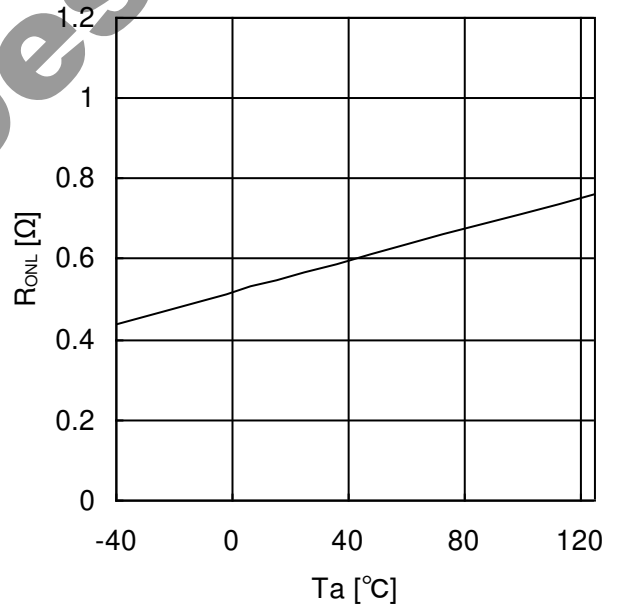


Figure 18. OUT1L ON-Resistance (I_{OUT1}=40mA)

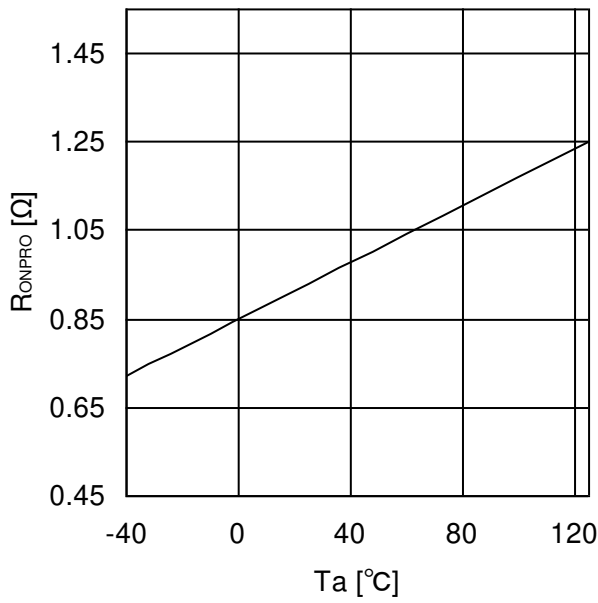


Figure 19. PROOUT ON-Resistance (I_{PROOUT}=40mA)

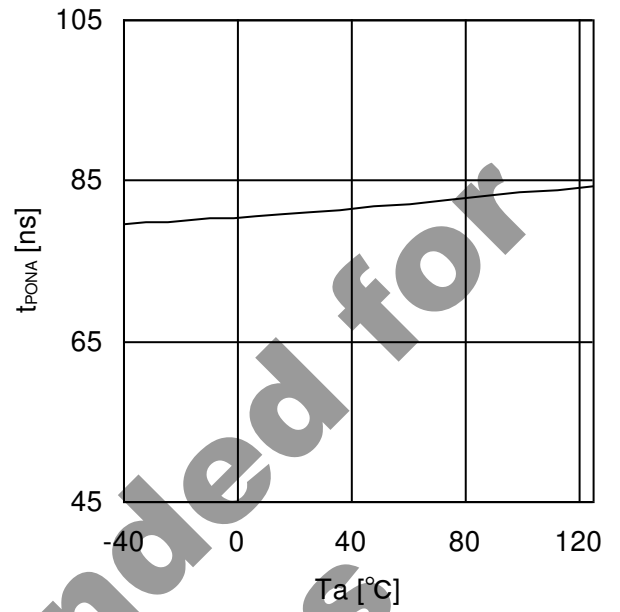


Figure 20. Turn ON time

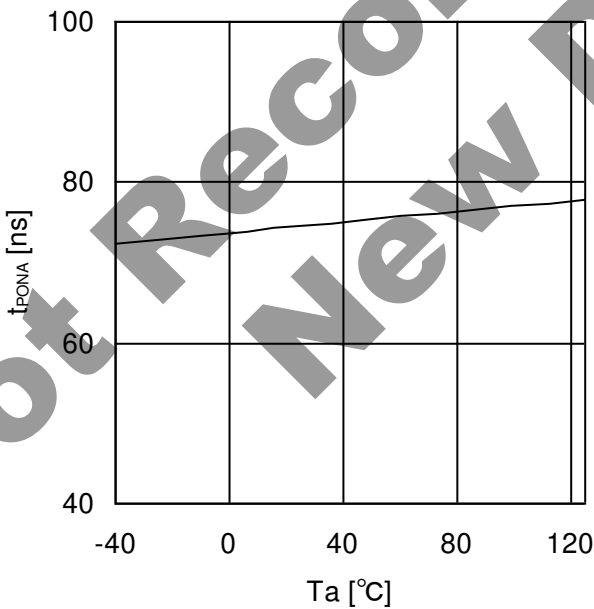


Figure 21. Turn OFF time

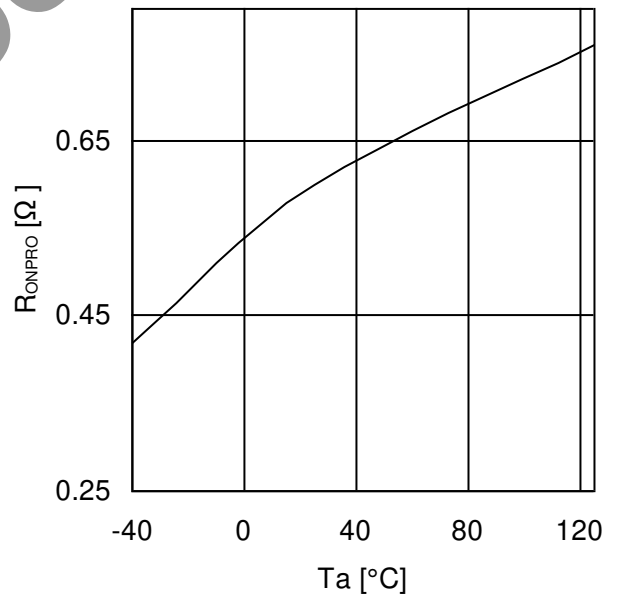


Figure 22. OUT2 ON-Resistance (I_{OUT2}=40mA)

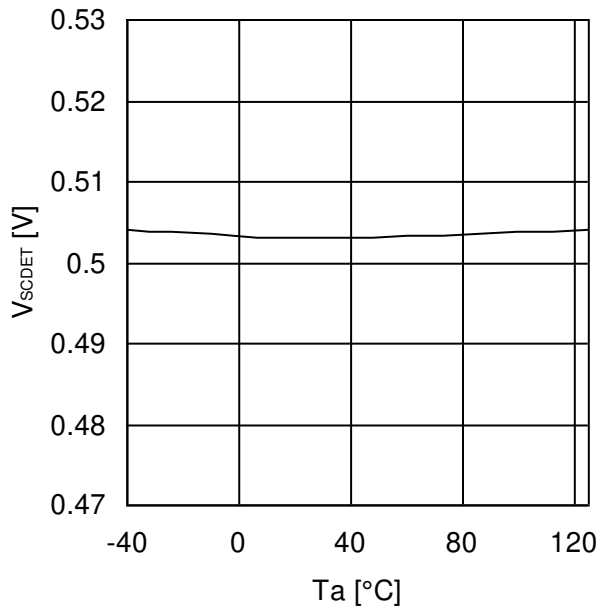


Figure 23. Short Current Detection Voltage

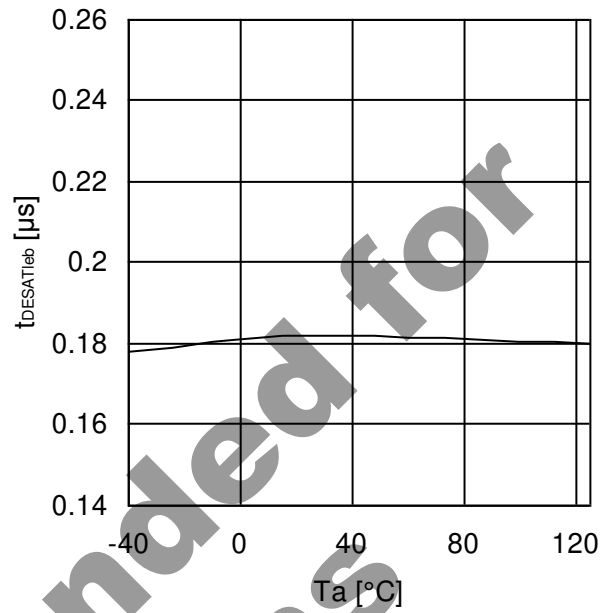


Figure 24. DESAT Leading Edge Blanking Time

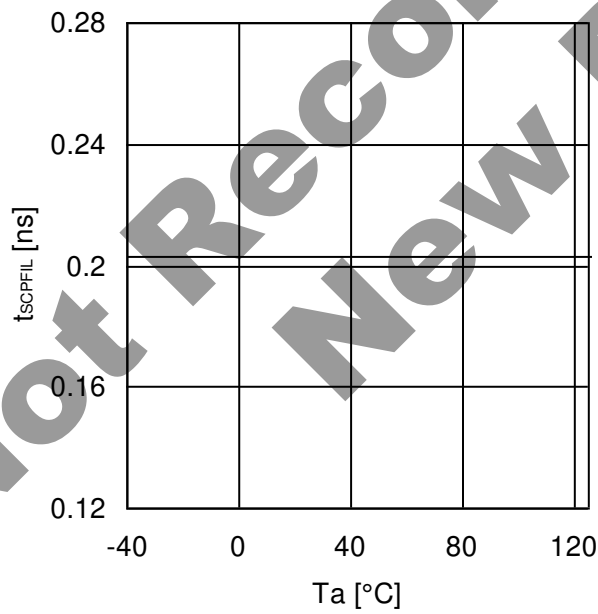


Figure 25. Short Current Detection Filter Time

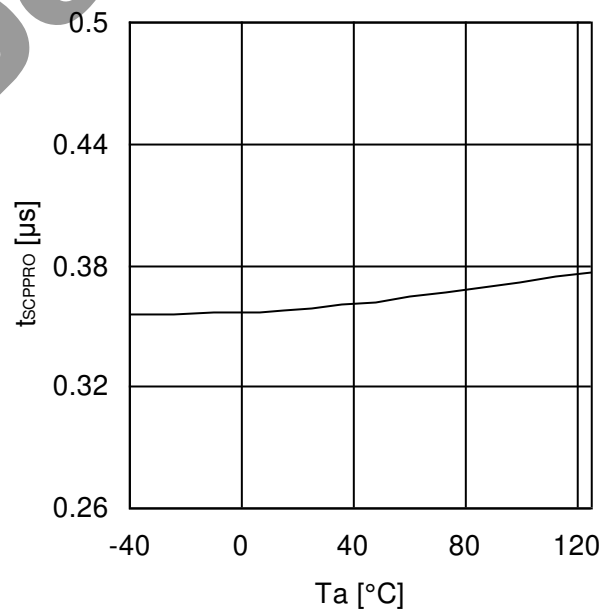


Figure 26. Short Current Detection Delay Time

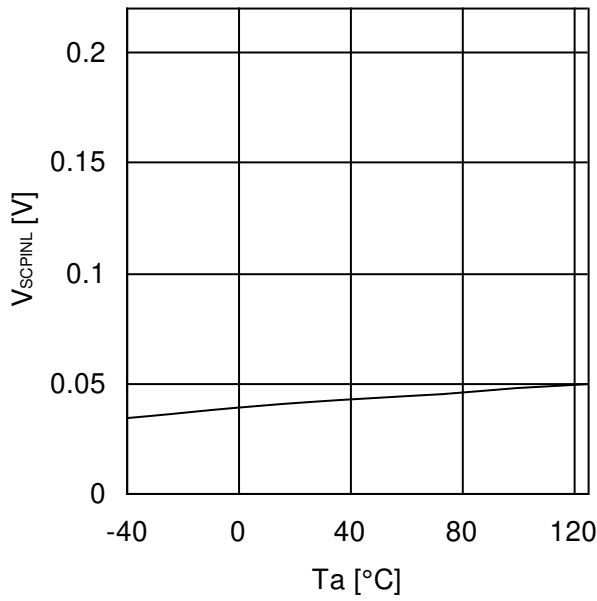


Figure 27. SCPIN Pin Low Voltage

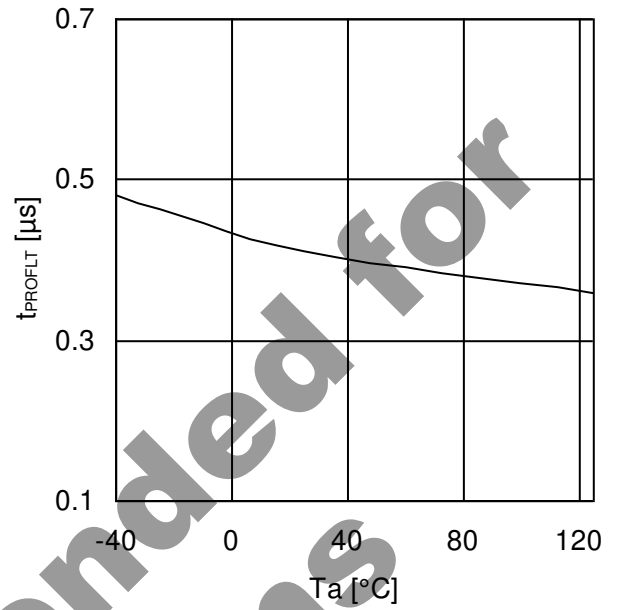


Figure 28. Output Delay Difference between PROOUT and FLT

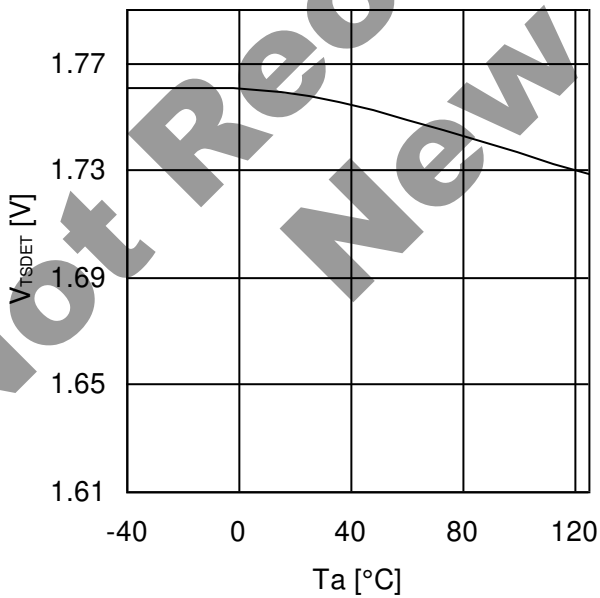


Figure 29. Thermal Detection Voltage

Application Information

1. Description of Pins and Cautions on Layout of Board

(1) V_BATT (Main Power Supply Pin)

This is the main power supply pin. Connect a bypass capacitor between V_BATT and GND1 in order to suppress voltage variations.

(2) GND1 (Input-side Ground Pin)

The GND1 pin is a ground pin on the input side.

(3) VCC2 (Output-side Positive Power Supply Pin)

The VCC2 pin is a positive power supply pin on the output side. To reduce voltage fluctuations due to OUT1H/L pin output current and due to the driving current of the internal transformers, connect a bypass capacitor between VCC2 and GND2 pins.

(4) VEE2 (Output-side Negative Power Supply Pin)

The VEE2 pin is a power supply pin on the output side. To suppress voltage fluctuations due to OUT1H/L pin output current and due to the driving current of the internal transformers, connect a bypass capacitor between the VEE2 and the GND2 pins. Connect the VEE2 pin to the GND2 pin when no negative power supply is used.

(5) GND2 (Output-side Ground Pin)

The GND2 pin is a ground pin on the output side. Connect the GND2 pin to the emitter / source of a power device.

(6) INA,INB,ENA (Control Input Terminal)

The INA,INB,ENA are pins used to determine output logic.

ENA	INB	INA	OUT1H	OUT1L
L	X	X	Hi-Z	L
H	H	X	Hi-Z	L
H	L	L	Hi-Z	L
H	L	H	H	Hi-Z

Fault state (FLT=L output) is released in rising of ENA(L→H).

(7) FLT (Fault Output Pin)

The FLT pin is an open drain pin used to output a fault signal when short circuit protection function (SCP) or thermal protection function is activated, and will be cleared at the rising edge of ENA.

Status	FLT
While in normal operation	Hi-Z
When a fault occurs (When SCP or thermal protection is activated)	L

(8) RDY (Ready Output Pin)

The RDY pin shows the status of three internal protection features which are V_BATT UVLO, VCC2 UVLO, and output state feedback (OSFB). The term 'output state feedback' shows whether PROOUT pin voltage (High or Low) corresponds to input logic or not.

Status	RDY
While in normal operation	Hi-Z
V_BATT UVLO or VCC2 UVLO or Output state feedback	L

(9) MODE (Mode Selection Pin of Output-side UVLO)

The MODE pin is a pin which selects internal threshold or external setting threshold for output-side UVLO.

MODE	Output-side UVLO threshold voltage
L (=GND2)	Setting by external. (Use UVLOIN pin)
H (=VCC2)	Fixed (=V _{UVLO2L}). (Connect UVLOIN pin to VCC2 pin)

(10) UVLOIN (Output-side UVLO Setting Input Pin)

The UVLOIN pin is a pin for deciding UVLO setting value of VCC2. The threshold value of UVLO can be set by dividing the resistance voltage of VCC2 and inputting such value. UVLOIN activates only at MODE pin=L. When MODE pin=H, connect UVLOIN pin to VCC2 pin.

(11) OUT1H, OUT1L(Output Pin)

The OUT1H pin is a source side pin used to drive the gate of a power device, and the OUT1L pin is a sink side pin used to drive the gate of a power device.

(12) OUT2 (Miller Clamp Pin)

This is the miller clamp pin for preventing a rise of gate voltage due to miller current of output element connected to OUT1. It also functions as a pin for monitoring gate voltage for miller clamp and OUT2 pin voltage become not more than VOUT2ON(typ 2.0V), miller clamp function operates. OUT2 should be connect to VEE2 when miller clamp function is not used.

(13) PROOUT (Soft Turn-OFF Pin)

This is a pin for soft turn-OFF of output pin when short-circuit protection is in action. It also functions as a pin for monitoring gate voltage for output state feedback function.

(14) SCPIN(Short Circuit Current Detection Pin)

The SCPIN pin is a pin used to detect current for short circuit protection. When the SCPIN pin voltage exceeds V_{SCDET}, SCP function will be activated. This may cause the IC to malfunction in an open state. To avoid such trouble, short-circuit the SCPIN pin to the GND2 pin when the short circuit protection is not used. In order to prevent the wrong detection due to noise, the noise filter time t_{SCPFIL} is set.

(15) VTSIN (Thermal Detection Pin)

The VTSIN pin is a temperature sensor voltage input pin, which can be used for thermal protection of an output device. If VTSIN pin voltage becomes V_{TSDET} or less, OUT1H/L pin is set to HiZ/L. IC may malfunction in the open status, so be sure to supply the VTSPIN more than V_{TSDET} if the thermal protection function is not used. In order to prevent the wrong detection due to noise, the noise mask time t_{TSMASK} is set. In addition, it can be used also as compulsive shutdown terminal other than a temperature sense by inputting a comparator output etc.

(16) RT (Switching Frequency Setting Pin for Switching Controller)

The RT pin is a pin used to make setting of switching frequency of switching controller. The switching frequency is determined by the resistance value connected between RT and GND1. The value of switching frequency is determined by the value of the resistor R_{RT}.

$$F_{SW}[kHz] = 1 / (7.3 \times 10^{-8} \times R_{RT} + 2.2 \times 10^{-4})$$

(17) FB (Error Amplifier Inverting Input Pin for Switching Controller)

This is a voltage feedback pin of the switching controller. This pin combine with voltage monitoring at overvoltage protection function and under voltage protection function for switching controller. When overvoltage or under voltage protection is activated, switching controller will be at OFF state (FET_G pin outputs Low). When the protection holding time (t_{DCDCLLS}) is completed, the protection function will be released. Under voltage function is not activated during soft-start.

(18) COMP (Error Amplifier Output Pin for Switching Controller)

This is the gain control pin of the switching controller. Connect a phase compensation capacitor and resistor.

(19) VREG (Input-side internal power supply pin)

This is the input-side internal power supply pin. Be sure to connect a capacitor between VREG and GND1 even when the switching controller is not used, in order to prevent oscillation and suppress voltage variation due to FET_G output current.

(20) FET_G (MOS FET Control Pin for Switching Controller)

This is a MOSFET control pin for the switching controller transformer drive.

(21) SENSE (Connection to the Current Feedback Resistor of the Switching Controller)

This is a pin connected to the resistor of the switching controller current feedback. This pin combines with current monitoring at overcurrent protection function for switching controller. When overcurrent protection is activated, switching controller will be at OFF state (FET_G pin outputs Low). When the protection holding time (t_{DCDCLLS}) is completed, the over-current function will be released.

2. Description of Functions and Examples of Constant Setting

(1) Miller Clamp Function

When OUT1=L and OUT2 pin voltage < V_{OUT2ON} , internal MOS of OUT2 pin is turned ON and miller clamp function operates.

IN	OUT2 pin input voltage	OUT2
L	Not more than V_{OUT2ON}	L
H	X	Hi-Z

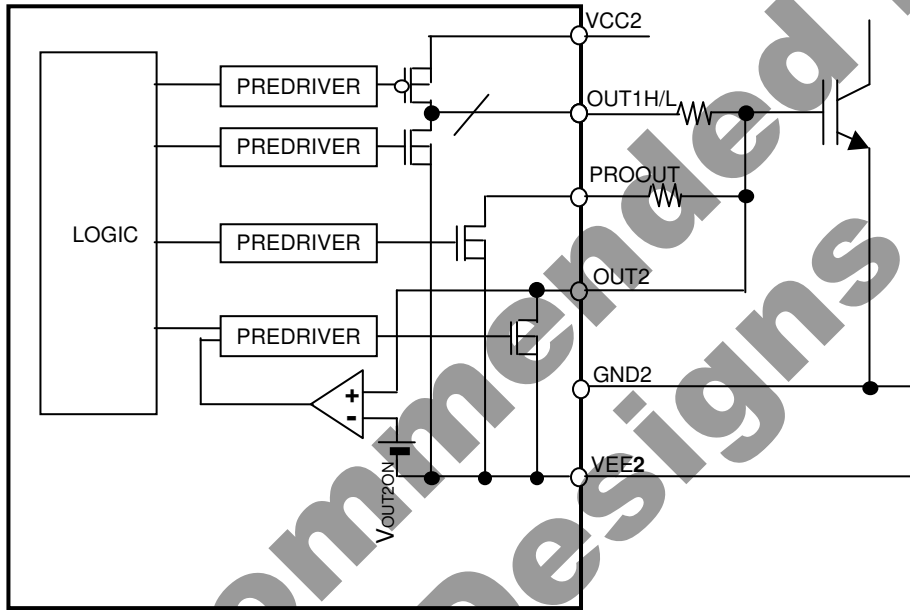


Figure 30. Block Diagram of Miller Clamp Function



Figure 31. Timing Chart of Miller Clamp Function

(2) Under Voltage Lockout (UVLO) Function

The BM60054FV-C incorporates the under voltage lockout (UVLO) function on V_BATT and VCC2. When the power supply voltage drops to the UVLO ON voltage, the OUT1H/L pin will output the "Hi-Z / L" and the FLT pin will output the "L" signal. When the power supply voltage rises to the UVLO OFF voltage, these pins will be reset. In addition, to prevent mis-triggers due to noise, mask time $t_{UVLOBATTFIL}$ and $t_{UVLO2FIL}$ are set on both voltage sides.

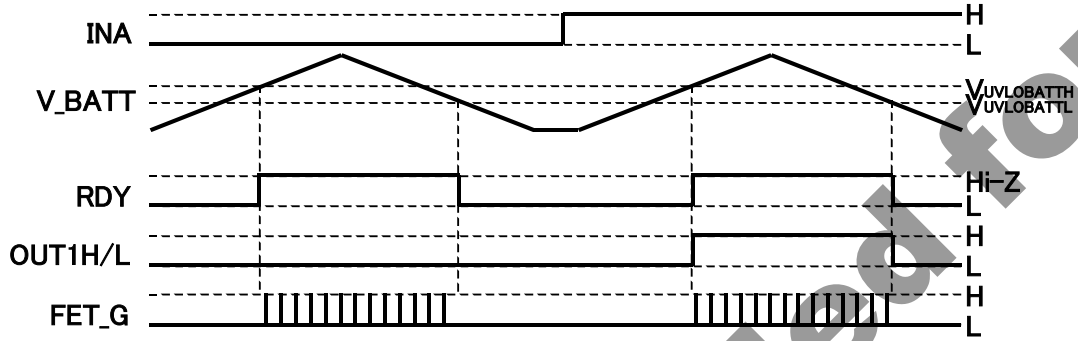


Figure 32. VBATT UVLO Function Operation Timing Chart

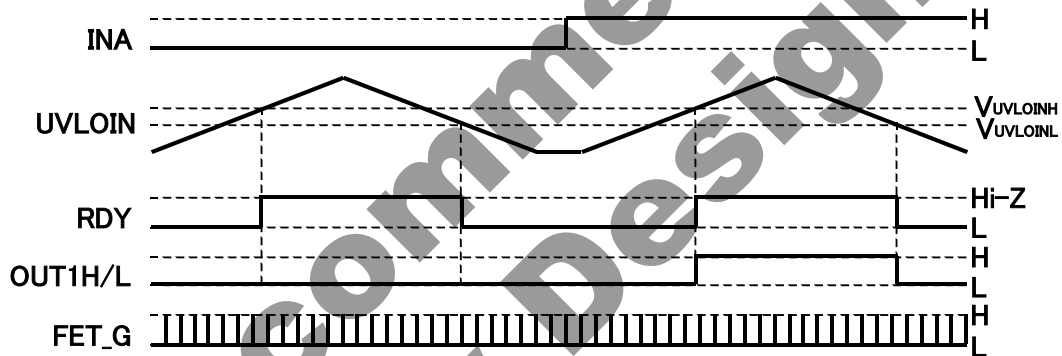


Figure 33. VCC2 UVLO Function Operation Timing Chart (MODE=L)

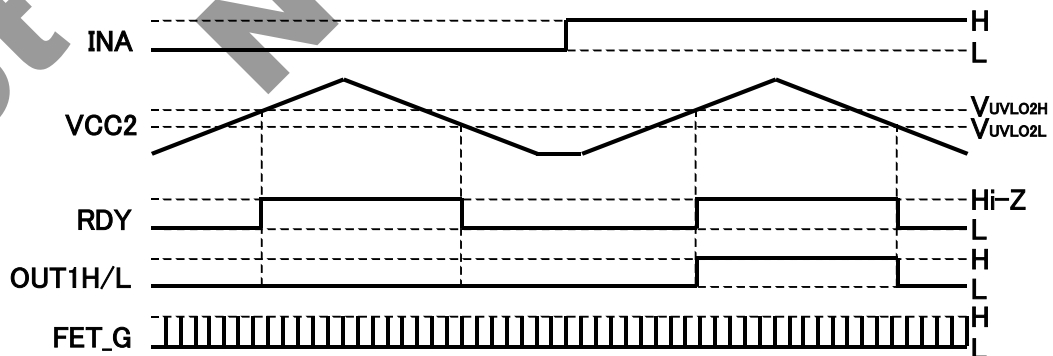


Figure 34. VCC2 UVLO Function Operation Timing Chart (MODE=H)

(3) Short Circuit Protection Function (SCP)

When the SCPIN pin voltage exceeds V_{SCDET} , the SCP function will be activated. When the SCP function is activated, the OUT1H/L pin voltage will be set to the "Hi-Z/Hi-Z" level and the PROOUT pin voltage will go to the "L" level first (soft turn-OFF). Next, After t_{STO} has passed, OUT1H/L pin become Hi-Z/L (PROOUT pin hold L). In addition, when OUT2 pin voltage $< V_{OUT2ON}$, miller clamp function operates.

When the rising edge is put in the ENA pin, the SCP function will be released.

When OUT1H/L=Hi-Z/L or Hi-Z/Hi-Z, internal MOSFET connected to SCPIN pin turns ON to discharge C_{BLANK} for desaturation protection function. When OUT1H/L=H/Hi-Z, internal MOSFET connected to SCPIN pin turns OFF.

$$V_{DESAT} [V] = V_{SCDET} \cdot \frac{R3 + R2}{R3} - V_{FD1}$$

$$V_{CC2_MIN} [V] > V_{SCDET} \cdot \frac{R3 + R2 + R1}{R3}$$

$$t_{BLANK\text{outemal}} [s] = - \frac{R2 + R1}{R3 + R2 + R1} \cdot R3 \cdot C_{BLANK} \cdot \ln \left(1 - \frac{R3 + R2 + R1}{R3} \cdot \frac{V_{SCDET}}{V_{CC2}} \right) + t_{DESAT\text{eb}}$$

V _{DESAT}	設定参考値		
	R1	R2	R3
4.0V	15 kΩ	39kΩ	4.7kΩ
4.5V	15 kΩ	47kΩ	5.1kΩ
5.0V	15 kΩ	51kΩ	5.1kΩ
5.5V	15 kΩ	27kΩ	2.4kΩ
6.0V	15 kΩ	33kΩ	2.7kΩ
6.5V	15 kΩ	62kΩ	4.7kΩ
7.0V	15 kΩ	47kΩ	3.3kΩ
7.5V	15 kΩ	20kΩ	1.3kΩ
8.0V	15 kΩ	82kΩ	5.1kΩ
8.5V	15 kΩ	62kΩ	3.6kΩ
9.0V	15 kΩ	33kΩ	1.8kΩ
9.5V	15 kΩ	75kΩ	3.9kΩ
10.0V	15 kΩ	68kΩ	3.3kΩ

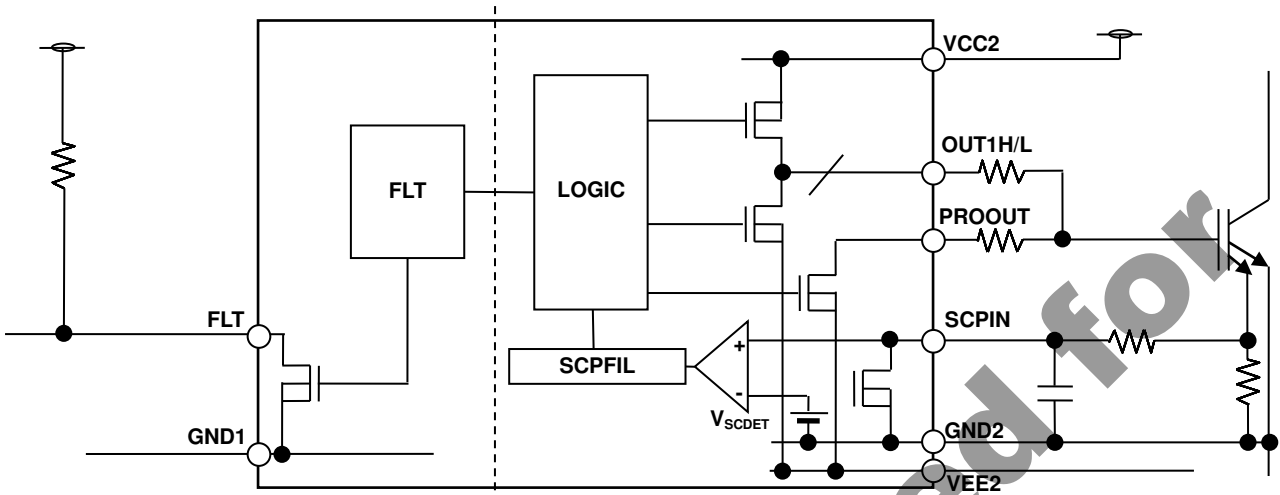


Figure 35. Block Diagram of Short Circuit Protection

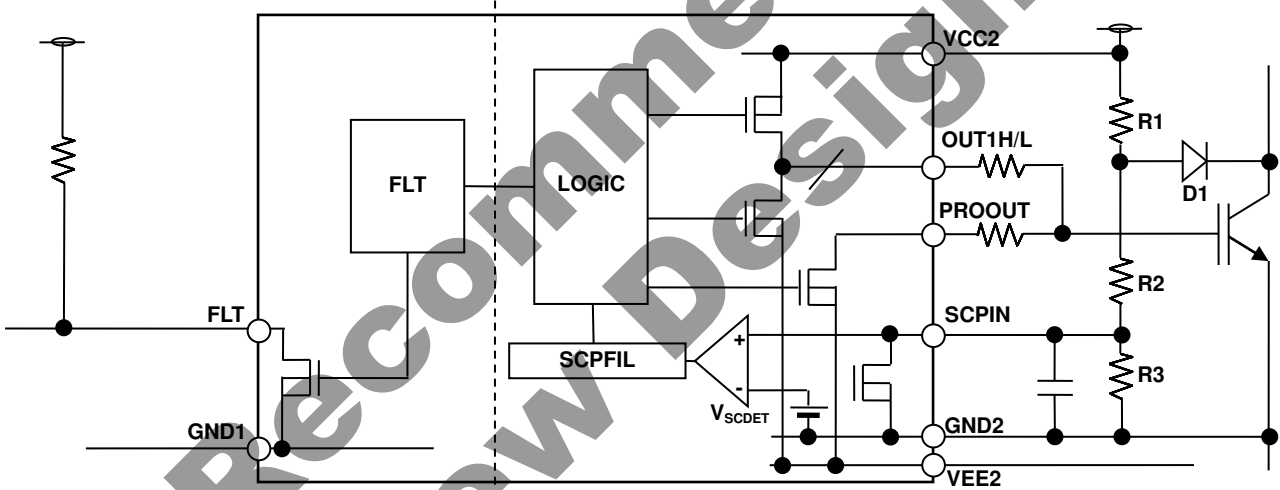


Figure 36. Block Diagram of DESAT

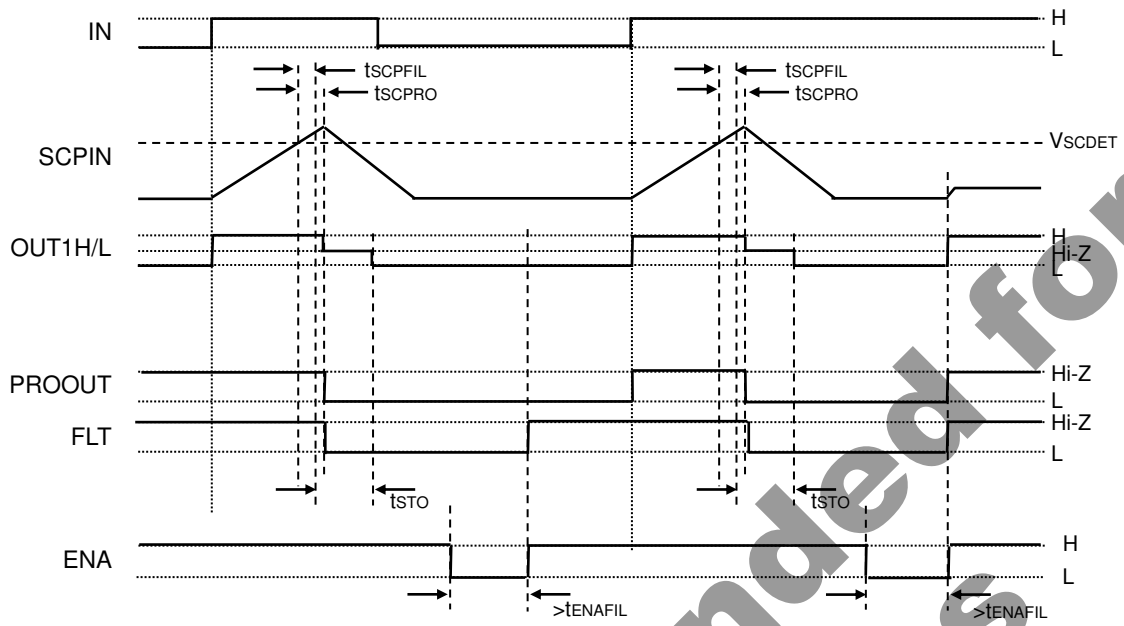


Figure 37. SCP Operation Timing Chart

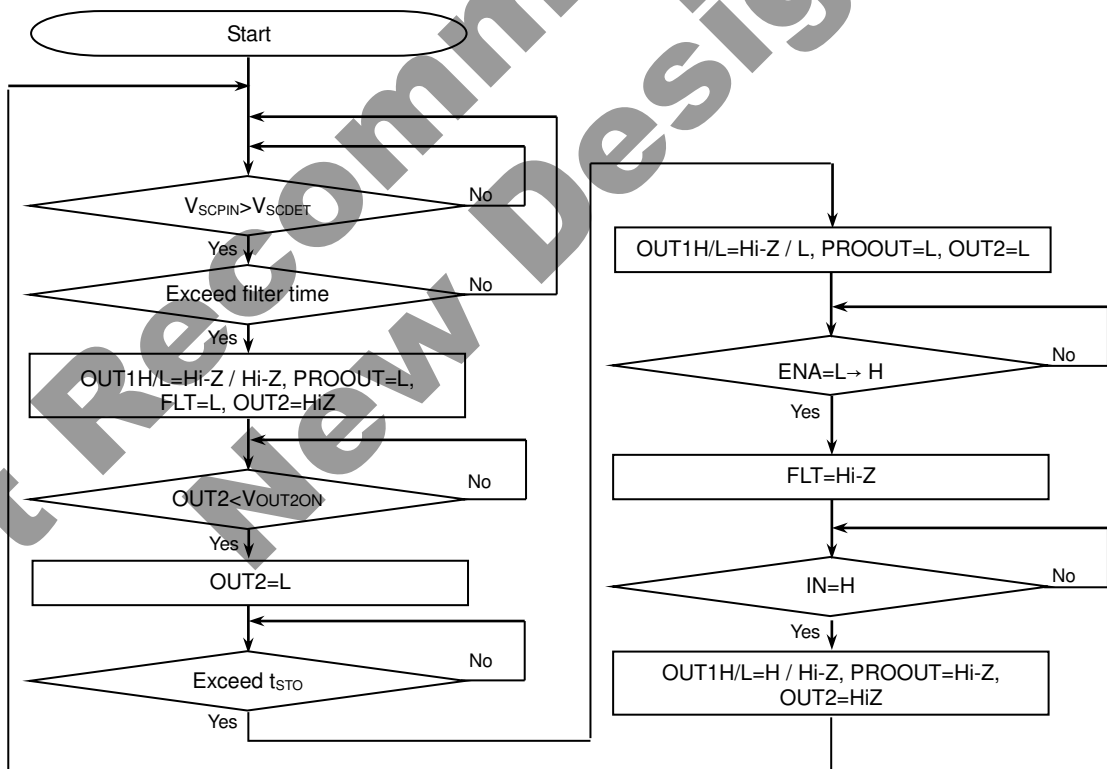


Figure 38. SCP Operation Status Transition Diagram

(4) Thermal Protection Function

When the VTSIN pin voltage becomes $V_{TSD\text{ET}}$ or less, the thermal protection function will be activated. When the thermal protection function is activated, the OUT1H/L pin voltage will be set to the “Hi-Z/Hi-Z” level and the PROOUT pin voltage will go to the “L” level first (soft turn-OFF). Next, when the VTSIN pin voltage rises to the threshold value and after t_{STO} has passed, OUT1H/L pin become Hi-Z/L (PROOUT pin hold L). In addition, when OUT2 pin voltage $< V_{\text{OUT}2\text{ON}}$, miller clamp function operates.

When the rising edge is put in the ENA pin, the thermal protection function will be released.

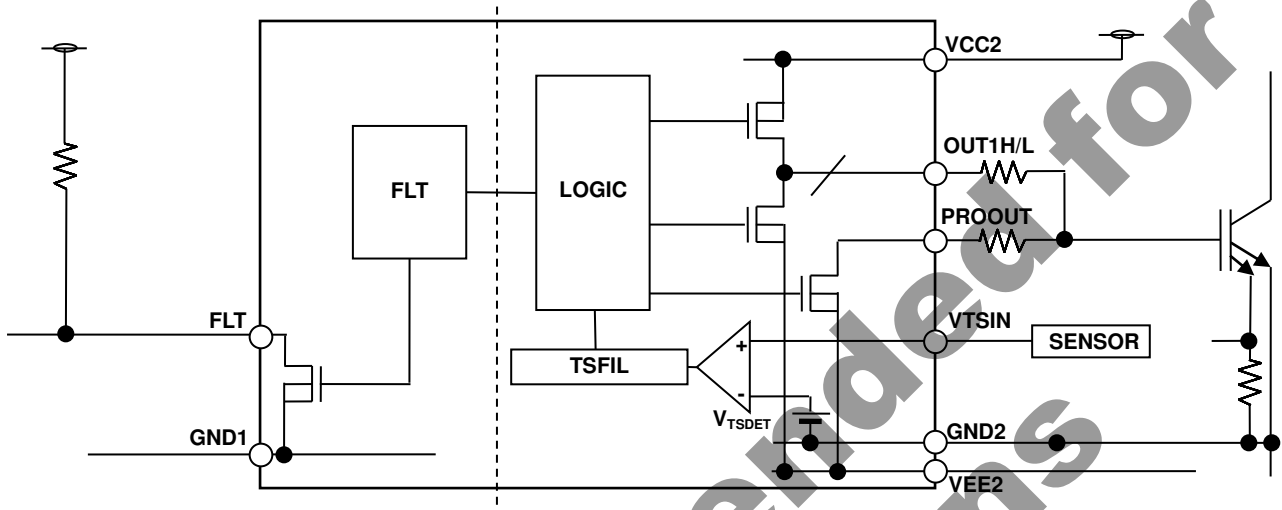


Figure 39. Block Diagram of thermal protection function

Not Recommended for New Designs

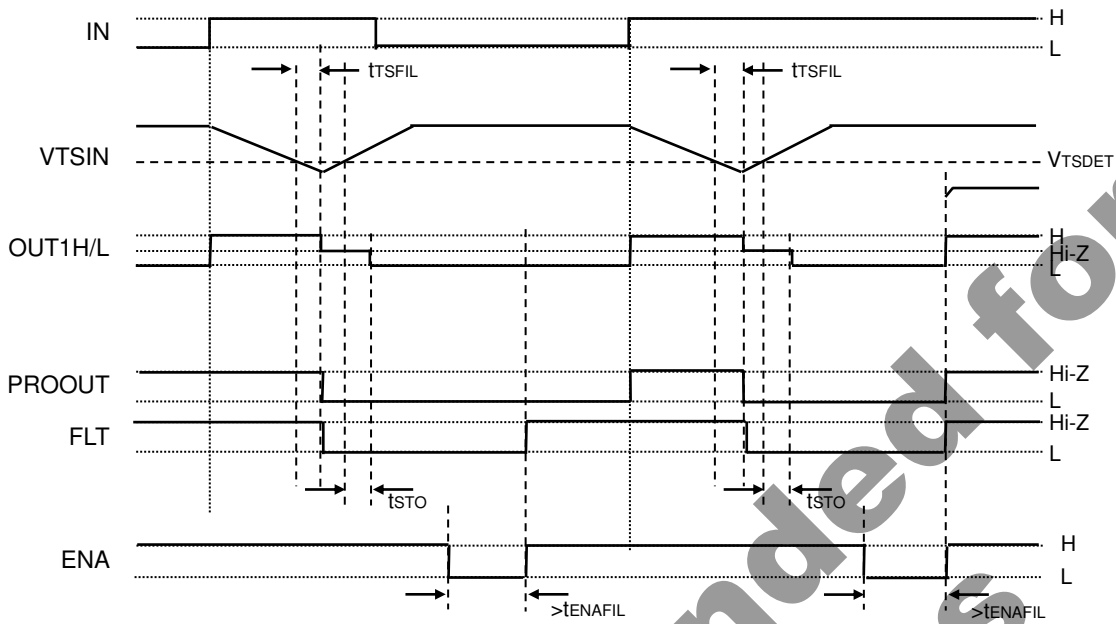


Figure 40. Thermal Protection Function Operation Timing Chart

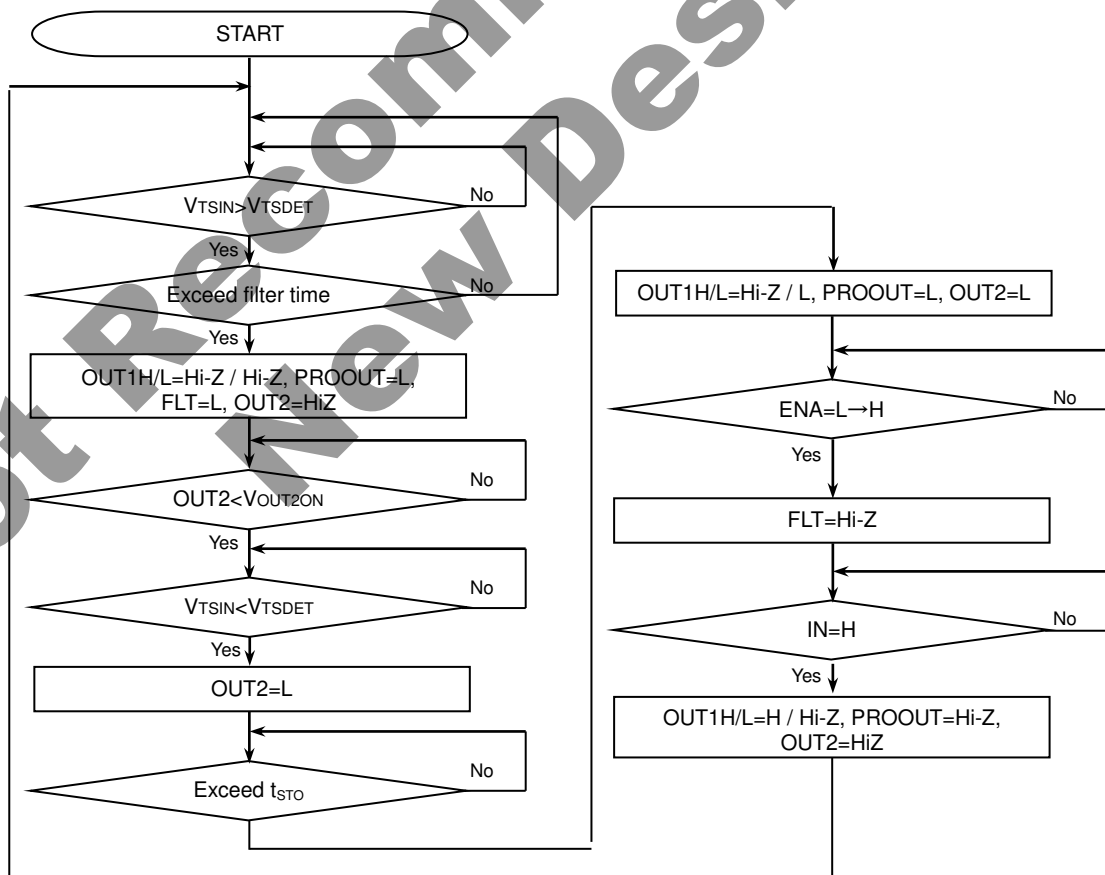


Figure 41. Thermal Protection Function Operation Status Transition Diagram

(5) Switching Controller

(a) Basic action

This IC has a built-in switching power supply controller which repeats ON/OFF synchronizing with internal clock set by RT pin. When VBATT voltage is supplied (VBATT > VUVLOBATT), FET_G pin starts switching by soft-start. Output voltage is determined by the following equation by external resistance and winding ratio “n” of flyback transformer (n= VOUT2 side winding number/VOUT1 side winding number)

$$V_{OUT2} = V_{FB} \times \{(R_1 + R_2)/R_2\} \times n [V]$$

(b) MAX DUTY

When, for example, output load is large, and voltage level of SENSE pin does not reach current detection level, output is forcibly turned OFF by Maximum On Duty (DONMAX).

(c) Protection function

The switching controller has protection function as overvoltage protection (OVP), under voltage protection (UVP), and over-current protection (OCP). OVP and UVP monitor the voltage of FB pin, OCP monitor the voltage of SENSE pin.

When the protection function is activated, switching controller will be OFF state (FET_G pin outputs Low). The protection holding time (tDCDCRLS) is completed, the protection function will be released. Under voltage function is not activated during soft-start.

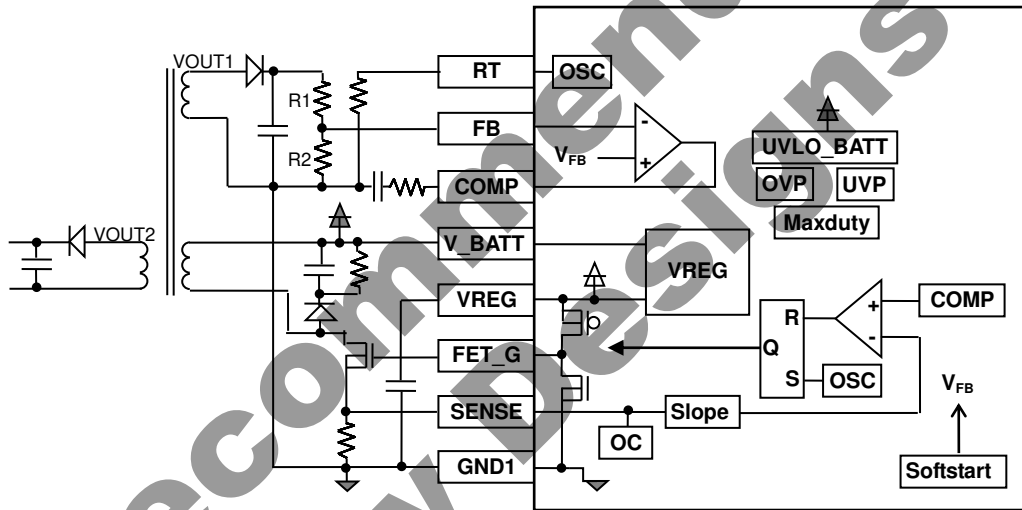


Figure 42. Block Diagram of switching controller

(d)The pin handling when not using switching controller
 When not using switching controller, please do pin handling as follows.

pin no.	pin name	processing method
21	RT	pull down in gnd1 by 68kΩ
22	FB	connect to VREG
23	COMP	connect to VREG
24	V_BATT	connect power supply
25	VREG	connect capacitor
26	FET_G	open
27	SENSE	connect to VREG

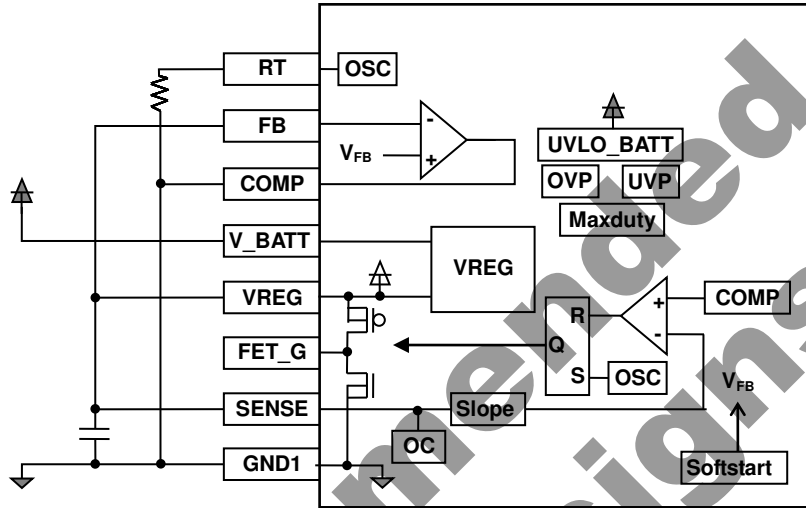


Figure 43. The pin handling when not using switching controller

(6) Gate State Monitoring Function

When gate logic and input logic of output device monitored with PROOUT pin are compared, a logic L is output from RDY pin when they disaccord. In order to prevent the detection error due to delay of input and output, OSFB filter time $t_{OSFBFIL}$ is provided.